### NCE N-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE4009S uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### **General Features**

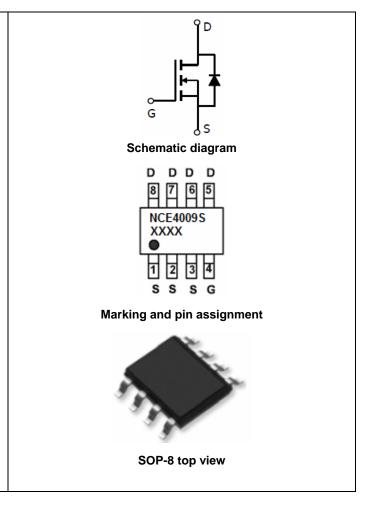
#### N-Channel

 $V_{DS} = 40V, I_{D} = 9A$ 

 $R_{DS(ON)}$  < 16m $\Omega$  @  $V_{GS}$ =10V

 $R_{DS(ON)}$  < 24m $\Omega$  @  $V_{GS}$ =4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package



**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE4009S	NCE4009S	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	40	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	9	Α
Drain Current-Continuous(T <sub>C</sub> =100℃)	I <sub>D</sub> (100℃)	6.4	Α
Pulsed Drain Current	I <sub>DM</sub>	40	Α
Maximum Power Dissipation	P <sub>D</sub>	2	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (Note 2)	R <sub>0JA</sub>	62.5	°C/W
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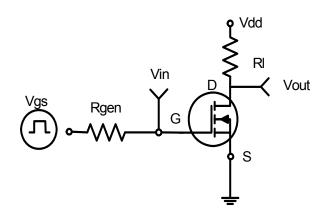


N-CH Electrical Characteristics ( $T_A=25$   $^{\circ}$ C unless otherwise noted)

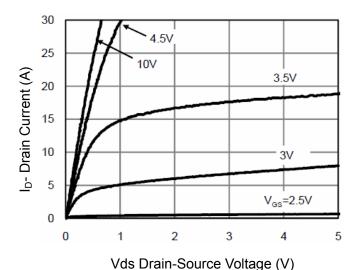
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	40	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1	1.5	2.0	V
Drain Course On Chata Basistanas	Б	V <sub>GS</sub> =10V, I <sub>D</sub> =8A	-	12.9	16	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	-	1 - 100	mΩ	
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =8A	33	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	\/ -20\/\/ -0\/	-	415	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =40V,V <sub>GS</sub> =0V V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA V <sub>GS</sub> =10V, I <sub>D</sub> =8A V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	-	112	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.UIVITIZ	-	11	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	4	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =20V, $R_L$ =2.5 $\Omega$	-	3	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{GEN}$ =3 $\Omega$	-	15	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	2	-	nS
Total Gate Charge	$Q_g$	\/ 00\/ L 0A	-	12	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	3.2	-	nC
Gate-Drain Charge	$Q_{gd}$	V <sub>GS</sub> =1UV	-	3.1	-	nC
Drain-Source Diode Characteristics			•	•		
Diode Forward Voltage (Note 3)	$V_{SD}$	V <sub>GS</sub> =0V,I <sub>S</sub> =9A	-	0.8	1.2	V



### N- Channel Typical Electrical and Thermal Characteristics (Curves)



**Figure 1:Switching Test Circuit** 



**Figure 3 Output Characteristics** 

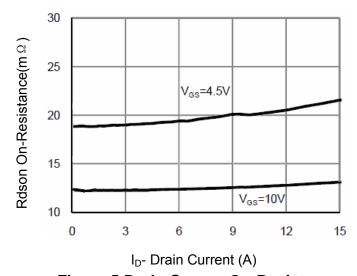
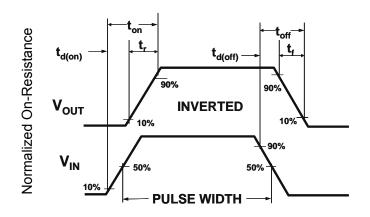
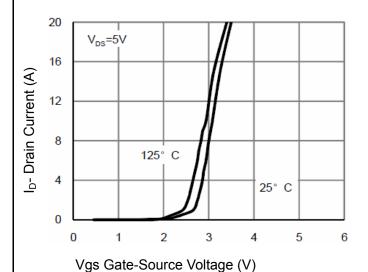


Figure 5 Drain-Source On-Resistance



**Figure 2:Switching Waveforms** 



**Figure 4 Transfer Characteristics** 

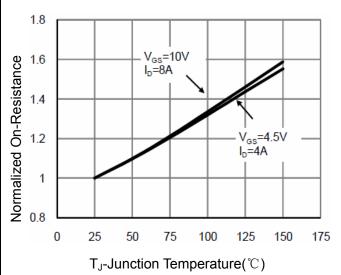
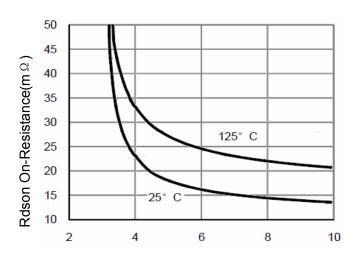


Figure 6 Drain-Source On-Resistance





Vgs Gate-Source Voltage (V)

### Figure 7 Rdson vs Vgs

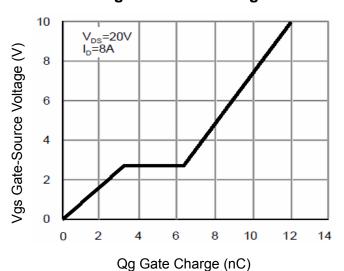


Figure 9 Gate Charge

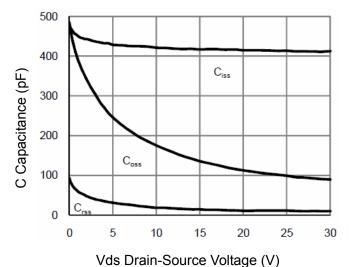
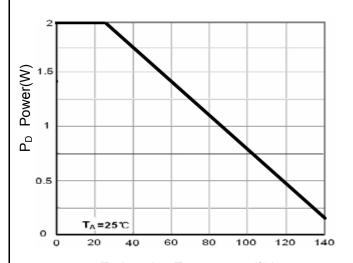


Figure 11 Capacitance vs Vds



 $T_J$ -Junction Temperature( $^{\circ}$ C) Figure 8 Power Dissipation

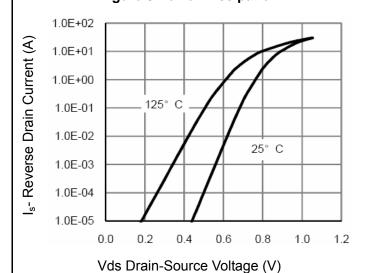
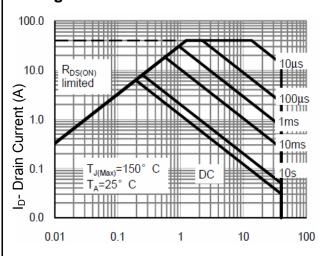


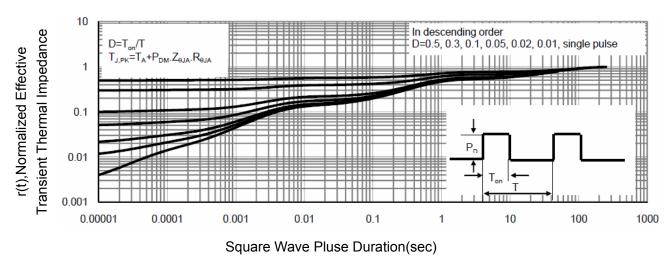
Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)

Figure 12 Safe Operation Area



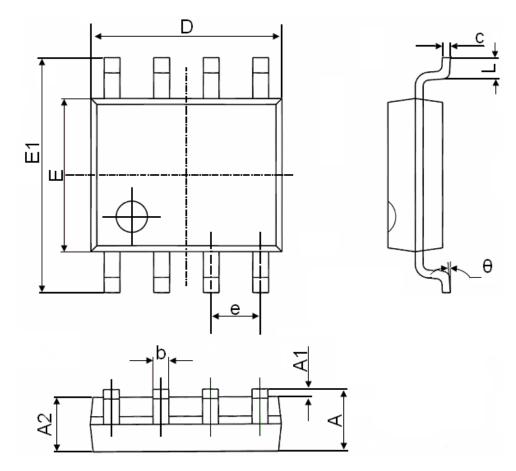


**Figure 13 Normalized Maximum Transient Thermal Impedance** 

**Pb Free Product** 



## **SOP-8 Package Information**



Cumbal	Dimensions	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	



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# NCE4009S

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